

Development and production
of laser and sorting systems

IL 2600 Sorting System

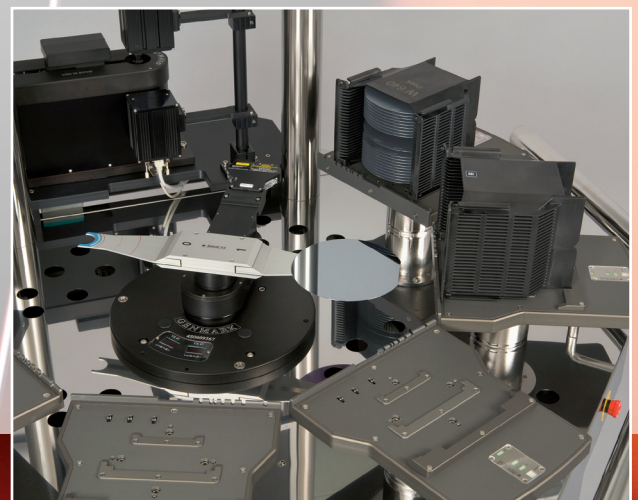


The InnoLas IL 2600 wafer sorting system can automatically sort, split, merge and transfer wafers from any slot / cassette to any other slot / cassette in a six cassette array.

Wafer sizes from 2" to 100mm and 100mm to 200mm can be handled in a single or multi-batch operation without the need of any mechanical adjustments.

The laser mark code read for verification can be located at any position on the front and/or backside of the wafer.

The basic model has one reading unit (OCR, BC412, T7) for reading the laser code on the frontside of the wafer. A second reading unit (OCR, BC412, T7) for reading the code on the backside of the wafer can be mounted as an option.



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Technical Specifications IL 2600 Series

HANDLING SYSTEM

Wafer sizes: 2", 2.25", 3", 3.25" and 100, 125, 150, 200mm
 Wafer transfer: Robot - double end effector
 Wafer alignment: Opto mechanical aligner
 Wafer handling: Vacuum or edge grip
 Number of stations: 6 stations (input/output)
 Throughput: 600 wafers/hr (transfer mode)
 250 wafers/hr (sort mode)

READING SYSTEM

Fonts: Dot Matrix (SEMI 5x9, 10x18, 15x23 and 9x17)
 Barcode (SEMI 412, IBM 412)
 2D Code (SEMI T7)
 Engrave Mode
 Others on request
 Checksum: SEMI, IBM

STANDARD OPTIONS

- Reading system for wafer front and / or backside
- Barcode hand scanner
- SECS/GEM host software
- Wafer thickness measurement

FACILITY REQUIREMENTS

Electrical: 230V AC / 1P / N / PE / 50Hz / 10A
 115V AC / 1P / N / PE / 60Hz / 20A
 Communication: Ethernet RJ45 connector
 Vacuum: -800mbar (23.6Hg) - Festo 8mm OD connection
 Weight: 400kg (882 lb) depending on options

CERTIFICATION

CE certified

